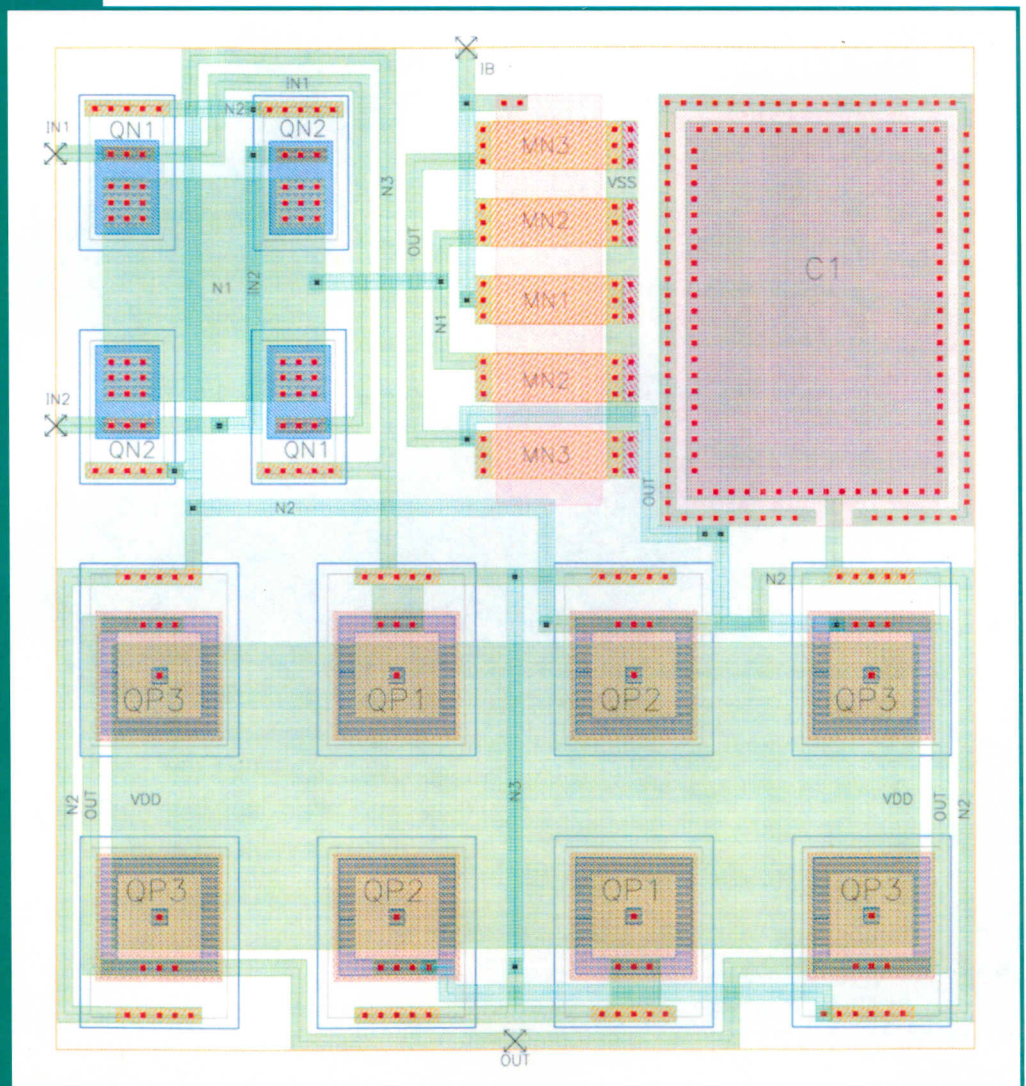


Second Edition

The Art of

# ANALOG LAYOUT



Alan Hastings

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